

PC Card Controllers

FEATURES

- A 144-terminal low-profile QFP (PGE), 144-terminal MicroStar BGA™ ball-grid array (GGU/ZGU) package, or a 209-terminal PBGA (GVF/ZVF) package
- 2.5-V core logic and 3.3-V I/O with universal PCI interfaces compatible with 3.3-V and 5-V PCI signaling environments
- Integrated low-dropout voltage regulator (LDO-VR) eliminates the need for an external 2.5-V power supply
- Mix-and-match 5-V/3.3-V 16-bit PC Cards and 3.3-V CardBus Cards
- A single PC Card or CardBus slot with hot insertion and removal
- Parallel interface to TI TPS2211A single-slot PC Card power switch
- Burst transfers to maximize data throughput with CardBus Cards
- Interrupt configurations: parallel PCI, serialized PCI, parallel ISA, and serialized ISA
- Serial EEPROM interface for loading subsystem ID, subsystem vendor ID, and other configuration registers
- Pipelined architecture for greater than 130-Mbps throughput from CardBus-to-PCI and from PCI-to- CardBus
- Up to five general-purpose I/Os
- Programmable output select for $\overline{\text{CLKRUN}}$
- Five PCI memory windows and two I/O windows available for the 16-bit interface
- Two I/O windows and two memory windows available to the CardBus socket
- Exchangeable-card-architecture- (ExCA-) compatible registers are mapped in memory and I/O space
- Intel™ 82365SL-DF and 82365SL register compatible
- Ring indicate, $\overline{\text{SUSPEND}}$, PCI $\overline{\text{CLKRUN}}$, and CardBus $\overline{\text{CCLKRUN}}$
- Socket activity LED terminal
- PCI bus lock ($\overline{\text{LOCK}}$)
- Internal ring oscillator

DESCRIPTION

The Texas Instruments PCI1510 device, a 144-terminal or a 209-terminal single-slot CardBus controller designed to meet the *PCI Bus Power Management Interface Specification for PCI to CardBus Bridges*, is an ultralow-power high-performance PCI-to-CardBus controller that supports a single PC card socket compliant with the *PC Card Standard* (rev. 7.2). The controller provides features that make it the best choice for bridging between PCI and PC Cards in both notebook and desktop computers. The *PC Card Standard* retains the 16-bit PC Card specification defined in the *PCI Local Bus Specification* and defines the 32-bit PC Card, CardBus, capable of full 32-bit data transfers at 33 MHz. The controller supports both 16-bit and CardBus PC Cards, powered at 5 V or 3.3 V, as required.

The controller is compliant with the *PCI Local Bus Specification*, and its PCI interface can act as either a PCI master device or a PCI slave device. The PCI bus mastering is initiated during CardBus PC Card bridging transactions. The controller is also compliant with *PCI Bus Power Management Interface Specification* (rev. 1.1).

All card signals are internally buffered to allow hot insertion and removal without external buffering. The controller is register-compatible with the Intel 82365SL-DF and 82365SL ExCA controllers. The controller internal data path logic allows the host to access 8-, 16-, and 32-bit cards using full 32-bit PCI cycles for maximum performance. Independent buffering and a pipeline architecture provide an unsurpassed performance level with sustained bursting. The controller can also be programmed to accept fast posted writes to improve system-bus utilization.



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Multiple system-interrupt signaling options are provided, including parallel PCI, parallel ISA, serialized ISA, and serialized PCI. Furthermore, general-purpose inputs and outputs are provided for the board designer to implement sideband functions. Many other features designed into the PCI1510 controller, such as a socket activity light-emitting diode (LED) outputs, are discussed in detail throughout this document.

An advanced complementary metal-oxide semiconductor (CMOS) process achieves low system power consumption while operating at PCI clock rates up to 33 MHz. Several low-power modes enable the host power management system to further reduce power consumption.

NOTE:

This product is for high-volume PC applications only. For a complete datasheet or more information contact support@ti.com.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
PCI1510GGU	ACTIVE	BGA	GGU	144	160	TBD	SNPB	Level-3-220C-168 HR
PCI1510GVF	NRND	BGA	GVF	209	90	TBD	Call TI	Level-3-220C-168 HR
PCI1510PGE	ACTIVE	LQFP	PGE	144	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PCI1510PGE4	ACTIVE	LQFP	PGE	144	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PCI1510ZGU	ACTIVE	BGA	ZGU	144	160	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR
PCI1510ZVF	ACTIVE	BGA	ZVF	209	90	Pb-Free (RoHS)	SNAGCU	Level-3-250C-1 WEEK

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

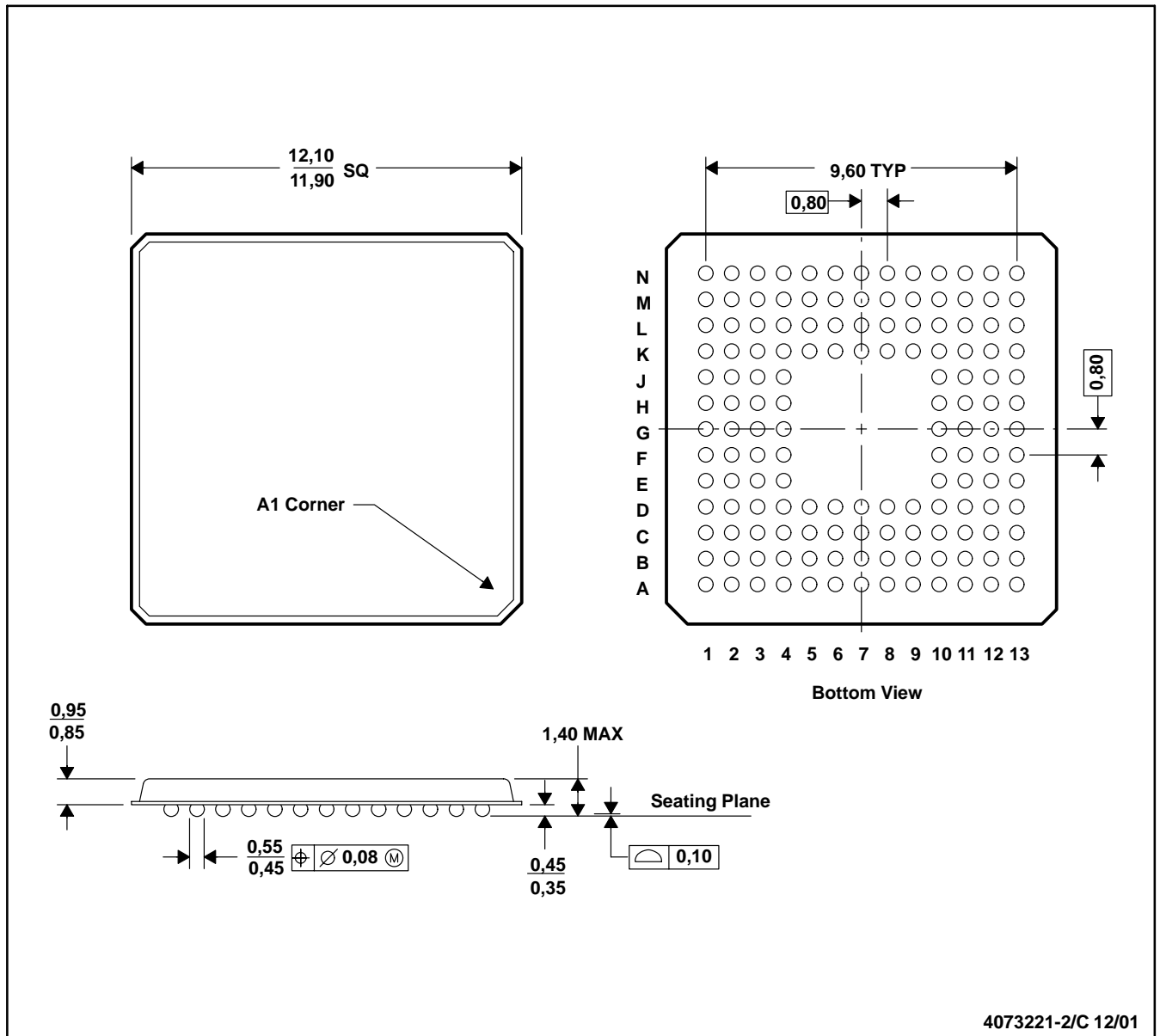
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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GGU (S-PBGA-N144)

PLASTIC BALL GRID ARRAY

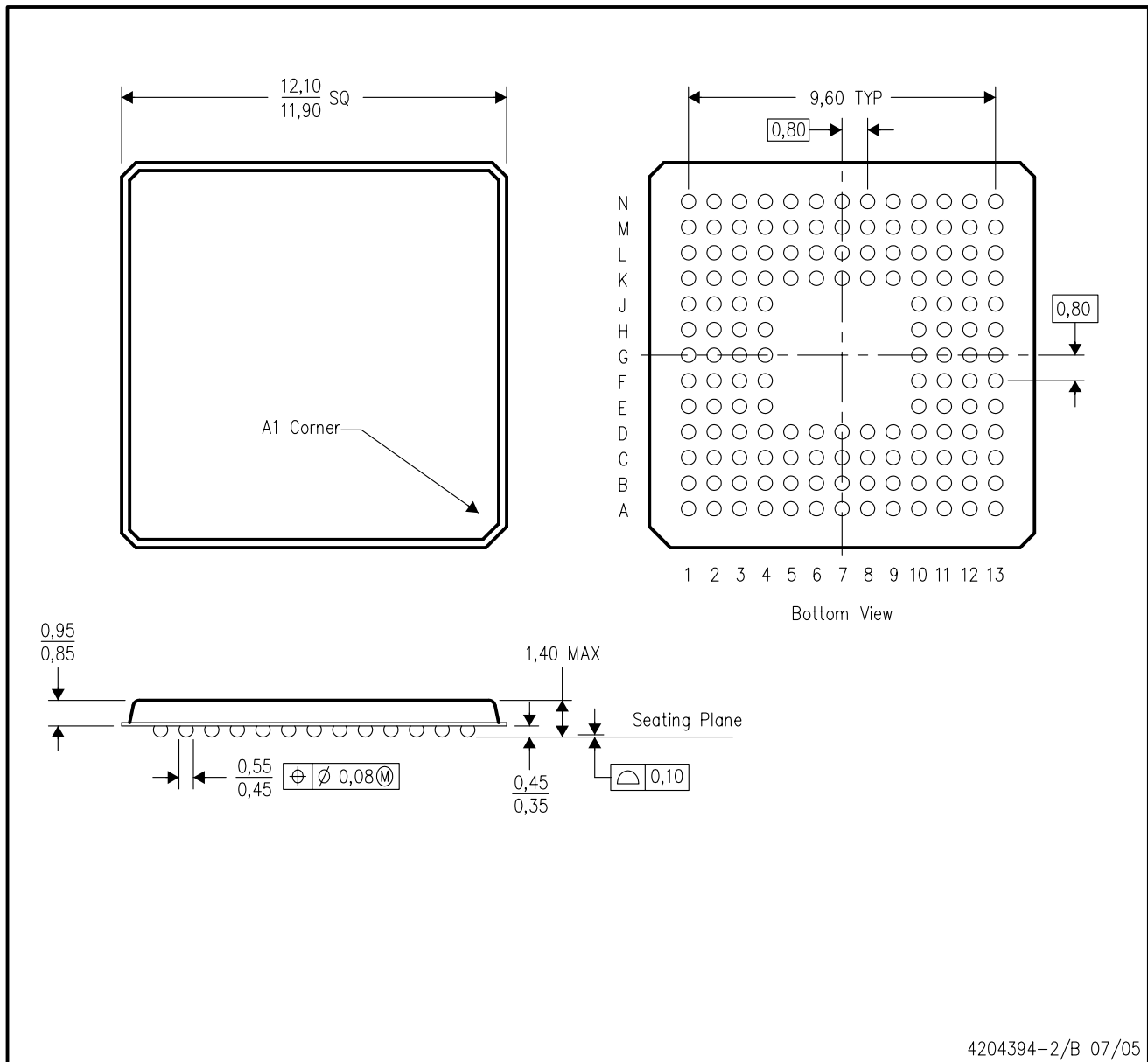


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice
 C. MicroStar BGA™ configuration

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ZGU (S-PBGA-N144)

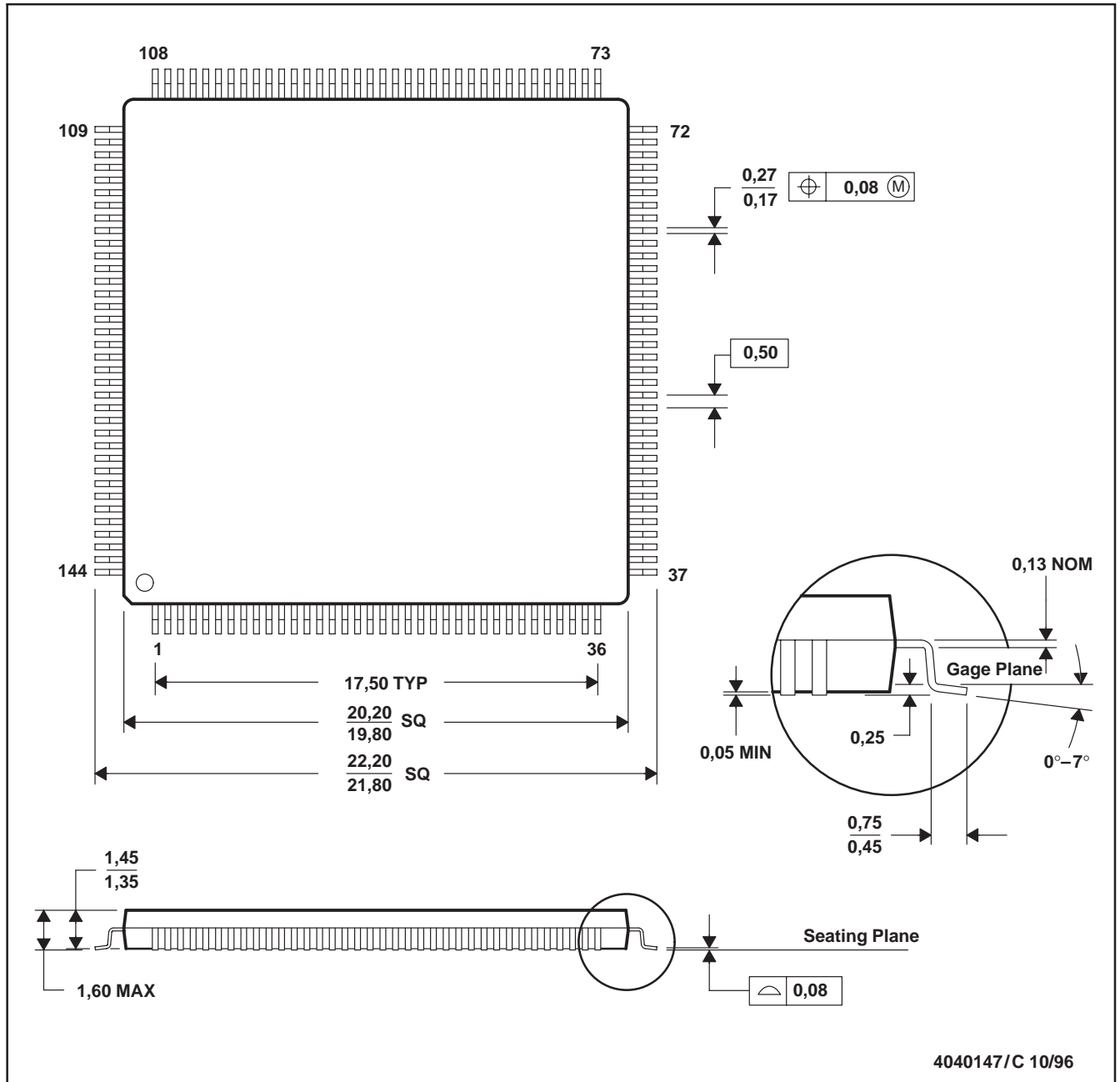
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Micro Star BGA configuration
 - D. This is a lead-free solder ball design.

PGE (S-PQFP-G144)

PLASTIC QUAD FLATPACK



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